Title (en)

Device for contacting a substrate.

Title (de)

Vorrichtung zum Kontaktieren eines Substrats.

Title (fr)

Dispositif pour établir un contact avec un substrat.

Publication

EP 0251158 A2 19880107 (EN)

Application

EP 87109022 A 19870623

Priority

DE 3622116 A 19860702

Abstract (en)

A device for contacting a substrate, preferably an electrical conductor, with spring parts that are in contact with the substrate at a plurality of points. Substrates of different diameters can be contacted without problem and for electrical conductors a high HF-impermeability is guaranteed. The device comprises at least one helical spring (5) arranged substantially annularly in a housing (1), with the helical windings (9) of the spring inclined at an angle alpha to the radial plane (10) perpendicular to the contact axis (11) When different sized substrates are inserted the windings turn, changing the angle alpha . This requires little force. Also the spacing of adjacent helical windings is maintained so that for electrical conductor substrates the same high HF impermeability is guaranteed for all conductor diameters.

IPC 1-7

H01R 9/05; H01R 17/12

IPC 8 full level

H01R 13/187 (2006.01)

CPC (source: EP)

H01R 13/187 (2013.01); H01R 24/38 (2013.01)

Cited by

EP0331959A3; GB2231449A; US6102746A; EP0430225A1; US5072070A; EP0395081A3; WO9002581A1

Designated contracting state (EPC)

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